

ADMER[™] NF468E

PE-Grade MFR: 4.0 Density: 0.92

Technical Data Sheet

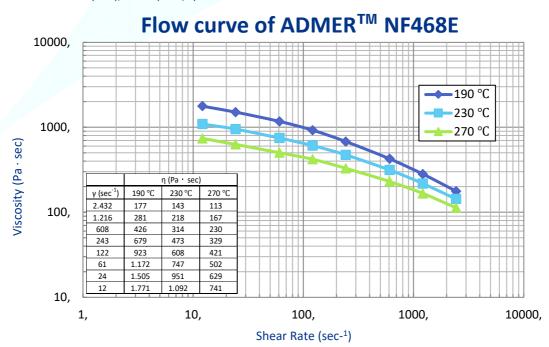
Preface

ADMER™ NF468E is a maleic anhydride grafted, PE-LLD-based tie resin, designed for multilayer pipes composed of PE, PEx or PE-RT with EVOH, PA or Aluminum. It offers advanced adhesion durability and good processability.

Properties

| Item | Value | Unit | Testing Method | | | |
|--|----------|----------|---------------------|--|--|--|
| MFR (190°C, 2.16kg) | 4.0 | g/10 min | ASTM D1238 | | | |
| Density | 0.92 | g/cm³ | ASTM D1505 | | | |
| Tensile Strength at Yield | 10.8 | MPa | ASTM D638 | | | |
| Tensile Strength at Brea | ak 18 | MPa | ASTM D638 | | | |
| Elongation at Break | > 500 | % | ASTM D638 | | | |
| Izod Impact Strength | No Break | J/m² | ASTM D256 | | | |
| Shore Hardness | 51 | D scale | ASTM D2240 | | | |
| Vicat Softening Point | 95 | °C | ASTM D1525 | | | |
| Melting Point | 120 | °C | ISO 11357-3 | | | |
| Oxidative Induction Tim | ne 55 | min | ISO 11357-6 (210°C) | | | |
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Vicat measured at load 1 (10N), rate A (50°C/h)





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Processing

The recommended processing temperatures for ADMER™ PE-Grades:

| C1 | C2 | C3 | C4 | ADMER Melt Temp. |
|---------|---------|---------|---------|------------------|
| 180 200 | 180 200 | 200 230 | 200 230 | 200 230 |

Maximum temperature: 300 °C; Temperatures above the upper limit or long residence times of molten resin may lead to decomposition of the polymer. Decomposition products may be carbon monoxide, carbon dioxide, hydrocarbons and water.

Whilst the extrusion process is either interrupted or terminated:

Less than 2 hours: Screw rotation can be stopped maintaining temperature.

More than 2 hours: Purge out and shut down in accordance with common procedure.

Handling

ADMER™ resins are supplied in the form of small, free flowing pellets and can be easily handled with commercially available equipment. We recommend to store ADMER™ at a dry and clean place at room temperature without sunlight exposure. Precaution should be taken in opening the package to avoid contamination by foreign materials.

Since ADMER™ is a non-hygroscopic material, it absorbs less moisture than non-polyolefin polymers. Therefore, ADMER™ does not require drying prior to processing.

ADMER™ can be re-used, recycled or incinerated with energy recovery. We do not recommend disposing of ADMER™ on a landfill. However, any disposal must comply with local regulations and recommendations.

Food Status

This information is only suitable for grade selection. For detailed information always refer to our Food Contact Status Declaration which is available on request. It is the full responsibility of the manufacturer of food contact materials or articles to ensure the suitability of above mentioned ADMER™ grade in its intended application.

EU: Monomers and additives are listed as authorized monomers/additives in Annex I of Regulation (EU) No. 10/2011 as amended to the current date. Please refer to our Food Contact Status Declaration regarding substances restricted by SMLs and Dual Use Additives.

USA: This ADMER™ grade conforms to FDA 21 CFR §175.105 (Adhesives). Please contact us for further details.



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Pipe Approvals

Approval for the usage of certain ADMER™ grades in pipe applications must always be obtained by pipe manufacturers. We will support customers in the pipe sector in that approval process by directly disclosing the required information to authorized testing laboratories on request. Evidence of ageing resistance of ADMER™ pipe grades according to DVGW W542 and ISO2578 has been obtained.



Disclaimer:

The information and numerical results are for information only and are given in good faith.

In view of numerous factors of which we are unaware and which are beyond our control regarding the use of our products, we cannot guarantee that this information covers all possible aspects of the subject. Moreover, we cannot accept any responsibility with regard to patents for applications and processes described.